Signal Integrity Effects in Custom IC and ASIC Designs

Description: "...offers a tutorial guide to IC designers who want to move to the next level of chip design by unlocking the secrets of signal integrity."
—Jake Buurma, Senior Vice President, Worldwide Research & Development, Cadence Design Systems, Inc.
- Covers signal integrity effects in high performance Radio Frequency (RF) IC
- Brings together research papers from the past few years that address the broad range of issues faced by IC designers and CAD managers now and in the future

A Wiley-IEEE Press publication

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